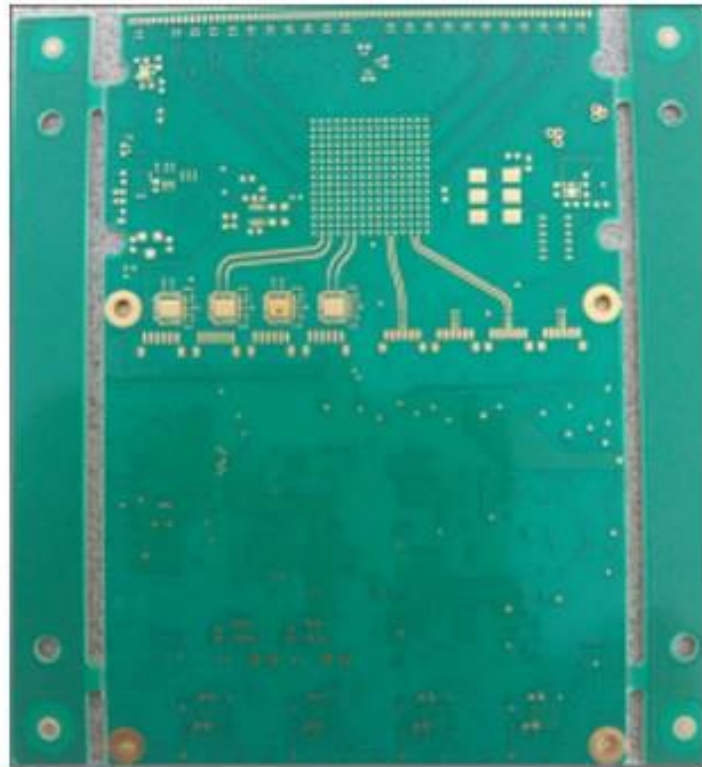


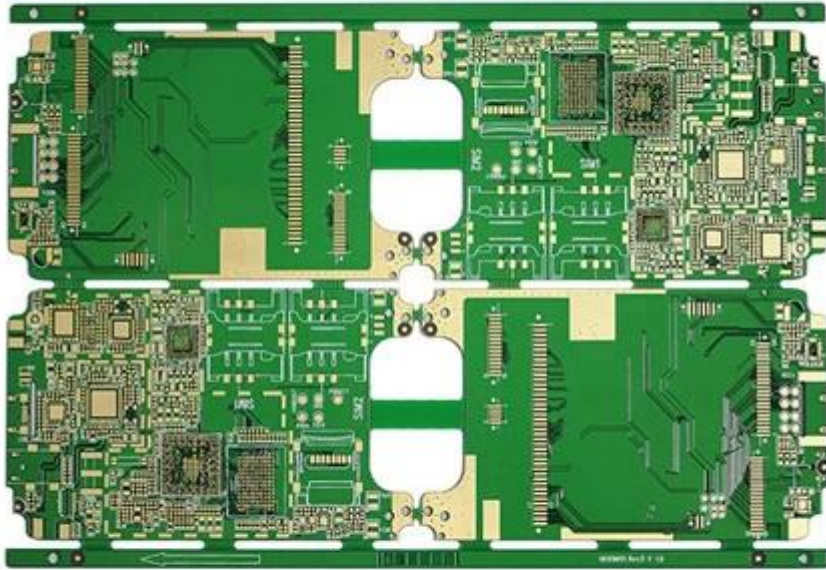
Copper Plate holes Minimum .025 AVG,. 020 min. Löcher dürfen nicht eingesteckt werden
 This PN required 10% Impedanz, 8mil Laser Drill, POFV, Stacked via, Laser blind via Drill Thru 6mil
 DK and Plug & plating Flat via

Pack mit colorless transparent Bubble Film, 25 Stk/Tasche, Put desiccant in Flanke, Put feuchte
 Indikator-Karte auf der Oberseite

Layer-Struktur

Custom Info Lyr	Image	Foil	Name
COMP		0.5oz	Foil 1/2oz(RTF)
6+/-0.9mil			R-5670K 1080 RC64%
			R-5670K 1080 RC64%
L2		0.5oz	Foil 1/2oz(RTF)
3.9+/-0.7mil			R-5670K 3313 RC54%
L3		0.5oz	
L4		0.5oz	R-5775K 0.200mm H/H 42.5"49"(3313*2)(RTF)
			R-5670K 1080 RC64%
6.9+/-1.5mil			R-5670K 3313 RC54%
L5		0.5oz	R-5775K 0.100mm H/H 42.5"49"(3313*1)(RTF)
L6		0.5oz	
			R-5670K 3313 RC54%
6.9+/-1.5mil			R-5670K 1080 RC64%
L7		0.5oz	R-5775K 0.200mm H/H 42.5"49"(3313*2)(RTF)
L8		0.5oz	
3.9+/-0.7mil			R-5670K 3313 RC54%
L9	0.5oz	Foil 1/2oz(RTF)	
		R-5670K 1080 RC64%	
6+/-0.9mil		R-5670K 1080 RC64%	
SOLD	0.5oz	Foil 1/2oz(RTF)	





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